

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently Amended) A heat spreading interposer comprising:  
at least one flexible electrical contact supported by a laminated housing such that a first end of said at least one flexible electrical contact projects outwardly from a first side of said housing and a second end of said at least one flexible electrical contact projects outwardly from a second side of said housing, wherein said laminated housing comprises a ~~lamination having~~ at least one layer of thermally conductive material supported by at least one coextensive layer of a dielectric material so that a portion of said at least one flexible electrical contact is (i) engaged, and (ii) in thermal communication with said at least one layer of thermally conductive material.

2. (Currently Amended) A heat spreading interposer according to claim 1 wherein said laminated housing comprises a plurality of dielectric layers and a plurality of thermally conductive layers.

3. (Previously presented) A heat spreading interposer according to claim 1 wherein said dielectric layers comprise a thermally conductive insulator.

4. (Previously presented) A heat spreading interposer according to claim 1 wherein said dielectric layers each have a thickness of about .003 inches to about .007 inches.

5. (Previously presented) A heat spreading interposer according to claim 1 wherein said at least one layer of thermally conductive material has a thickness of about .001 inches to about .005 inches.

6. (Previously presented) A heat spreading interposer according to claim 1 wherein said portion of said at least one flexible electrical contact is engaged with an annular edge of each of said at least one layers of thermally conductive material.

7. (Currently Amended) A heat spreading interposer according to claim 1 wherein said laminated housing defines a plurality of holes each having a thermally conductive liner that is arranged in thermal communication with said at least one layer of thermally conductive material wherein each of said flexible electrical contacts are thermally engaged with a portion of said liner.

8. (Currently Amended) A heat spreading interposer according to claim 1 wherein said at least one layer of thermally conductive material is sized larger than said laminated housing so as to form at least one wing

projecting outwardly from at least one edge of said laminated housing so as to dissipate heat into the ambient environment.

9. (Previously presented) A heat spreading interposer according to claim 8 wherein said at least one wing is engaged in thermal communication with a heat sink.

10. (Previously presented) A heat spreading interposer according to claim 8 wherein at least one discrete wing is thermally bonded to at least one thermally conductive layer.

11. (Currently Amended) A heat spreading interposer comprising: plurality of compressible electrical contact elements each having a first end and a second end and supported by a laminated housing so that said first end projects outwardly from a first side of said laminated housing and said second end projects outwardly from a second side of said laminated housing; wherein said laminated housing is formed from at least one layer of thermally conductive material supported by at least one coextensive layer of a dielectric material so that a portion of each of said plurality of compressible electrical contacts engages an annular edge of said at least one layers of thermally conductive material so as to be in thermal communication with said at least one layer of thermally conductive material.

12. (Previously presented) A heat spreading interposer according to claim 11 wherein at least one thermally conductive layer comprises a lead frame and said two layers of dielectric material comprise a polymer disposed in surrounding relation to portions of said lead frame.

13. (Currently Amended) A heat spreading interposer according to claim 11 wherein said laminated housing defines a plurality of holes each having a portion of said lead frame arranged in thermal communication one of said compressible electrical contacts.

14. (Currently Amended) A heat spreading interposer according to claim 11 wherein said lead frame is sized larger than said laminated housing so as to form at least one wing projecting outwardly from at least one edge of said laminated housing so as to form a heat radiator to dissipate heat into the ambient environment.

15. (Previously presented) A heat spreading interposer according to claim 14 wherein said at least one wing is engaged in thermal communication with a heat sink.

16. (Previously presented) A heat spreading interposer according to claim 14 wherein at least one discrete wing is thermally bonded to a portion of said lead frame.

17. (Currently Amended) A method of heat dissipation for an electronic device, comprising:

providing an interposer comprising plurality of flexible electrical contacts supported by a laminated housing wherein said housing is formed from at least one layer of thermally conductive material supported by at least one coextensive layer of a dielectric material so that a portion of each of said plurality of flexible electrical contacts is (i) engaged, and (ii) in thermal communication with said at least one layer of thermally conductive material;

a. positioning said interposer intermediate an electronic device and a printed circuit board; and

b. conducting heat away from said electronic device through said at least one layer of thermally conductive material.

18. (Original) The method of claim 17 further comprising providing a heat transfer wing to said at least one layer of thermally conductive material.

19. (Original) The method of claim 18 wherein said heat transfer wing is thermally engaged with a heat transfer device.

20. (Original) The method of claim 19 wherein said heat transfer device is selected from the group of heat transfer devices consisting of printed circuit boards, heat transfer devices attached to printed circuit boards, fins

extended into ambient air from said thermally conductive material, passive heat transfer devices, pins associated with the electronic device, and active heat transfer devices.

21. (Previously presented) The method of claim 17 wherein said interposer connects at least one of a land grid array mounted electronic device and a pin grid array mounted electronic device.

22. (Canceled)

23. (Canceled)